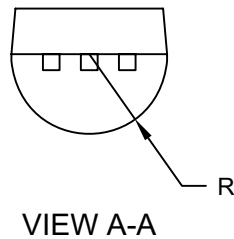
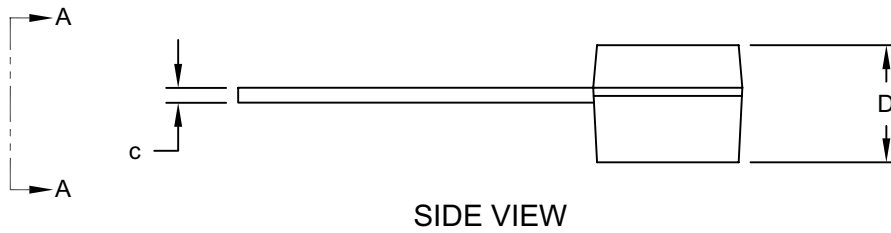
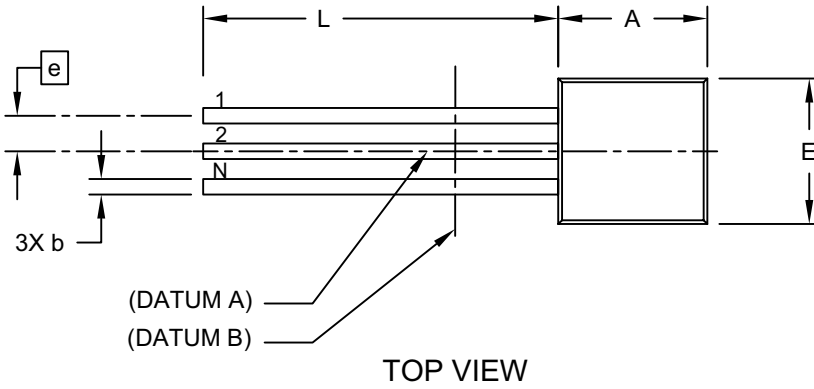


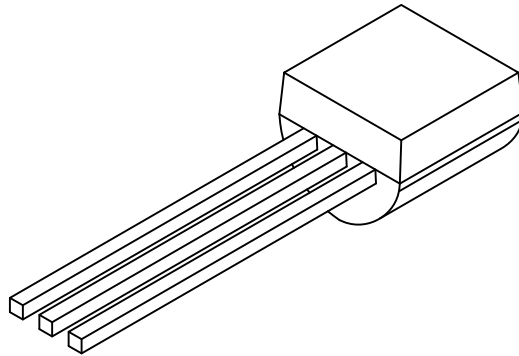
3-Lead Plastic Transistor Outline (TO) [TO-92]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



3-Lead Plastic Transistor Outline (TO) [TO-92]

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| | | Units | INCHES | | |
|------------------------|---|-------|----------|-----|------|
| Dimension Limits | | | MIN | NOM | MAX |
| Number of Pins | N | | 3 | | |
| Pitch | e | | .050 BSC | | |
| Bottom to Package Flat | D | .125 | - | | .165 |
| Overall Width | E | .175 | - | | .205 |
| Overall Length | A | .170 | - | | .210 |
| Molded Package Radius | R | .080 | - | | .105 |
| Tip to Seating Plane | L | .500 | - | | - |
| Lead Thickness | c | .014 | - | | .021 |
| Lead Width | b | .014 | - | | .022 |

Notes:

1. Dimensions D and E do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .005" per side.
2. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-101 Rev C Sheet 2 of 2

